

Claims

- [c1] What is claimed is:
1. A wafer holder for semiconductor manufacturing devices, the wafer holder having a wafer-carrying surface and comprising:
an electrical circuit formed either on a surface other than the wafer-carrying surface of the wafer holder, or else inside it;
and
electrodes for supplying power to said electrical circuit, said electrodes being separated by an interval that is 10% or more of the thickness of the wafer holder.
- [c2] 2. The wafer holder set forth in claim 1, wherein one or more metals selected from the group consisting of tungsten, molybdenum and tantalum are incorporated into portions of said electrodes that are directly connected to said circuit.
- [c3] 3. A semiconductor manufacturing device wherein the wafer holder set forth in claim 1 is installed.
- [c4] 4. A semiconductor manufacturing device wherein the wafer holder set forth in claim 2 is installed.